

GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2016/05/31	Phebe Su
A1			Add DIM	2016/08/19	Phebe Su

NOTES :

1.Material :

Housing/Slide : High temperature thermoplastic,UL94-V0.
Housing Color : Black/Slide Color : Ivory

Micro-SD Terminal : Copper Alloy.

Micro-SD C/D PIN & GND PIN : Copper Alloy.

Micro-SD Lock Pin : Stainless.

Cover : Stainless.

Hook/Spring : Stainless.

2.Finish :

Terminal :

Underplate : Ni over all.

Solder tail : Lead Free over Ni plate.

Contact Area : Au over Ni plate.

C/D PIN & GND PIN :

Underplate : Ni over all.

Solder tail : Lead Free over Ni plate.

Contact Area : Au over Ni plate.

Cover :

Underplate : Ni over all.

Solder tail : Au over Ni plate.

3.Solder tail Coplanarity Must Be Within 0.10 mm.

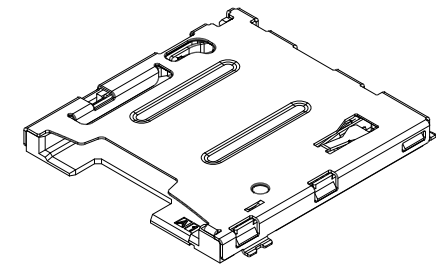
4.C/D : Card Detect Switch.

5.GND : Ground

6.Solder Tail Burr Must Be WithIN 0.10Max

7.Signal Terminal Contact Area Will Be Smooth

8.There can't be things to press and hold on the products surface

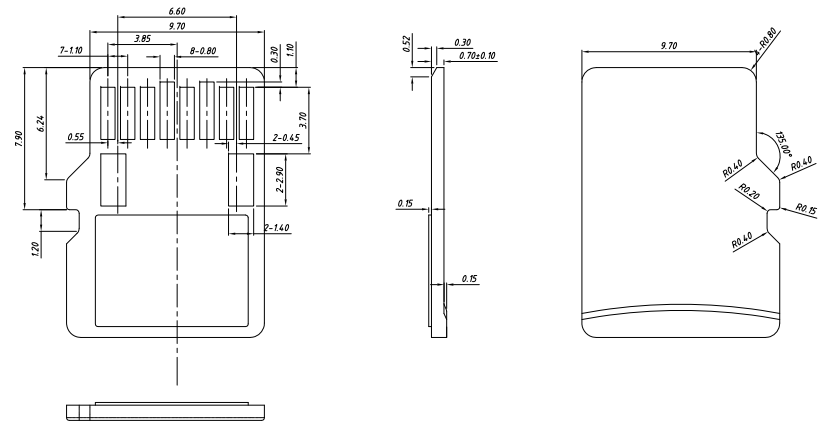
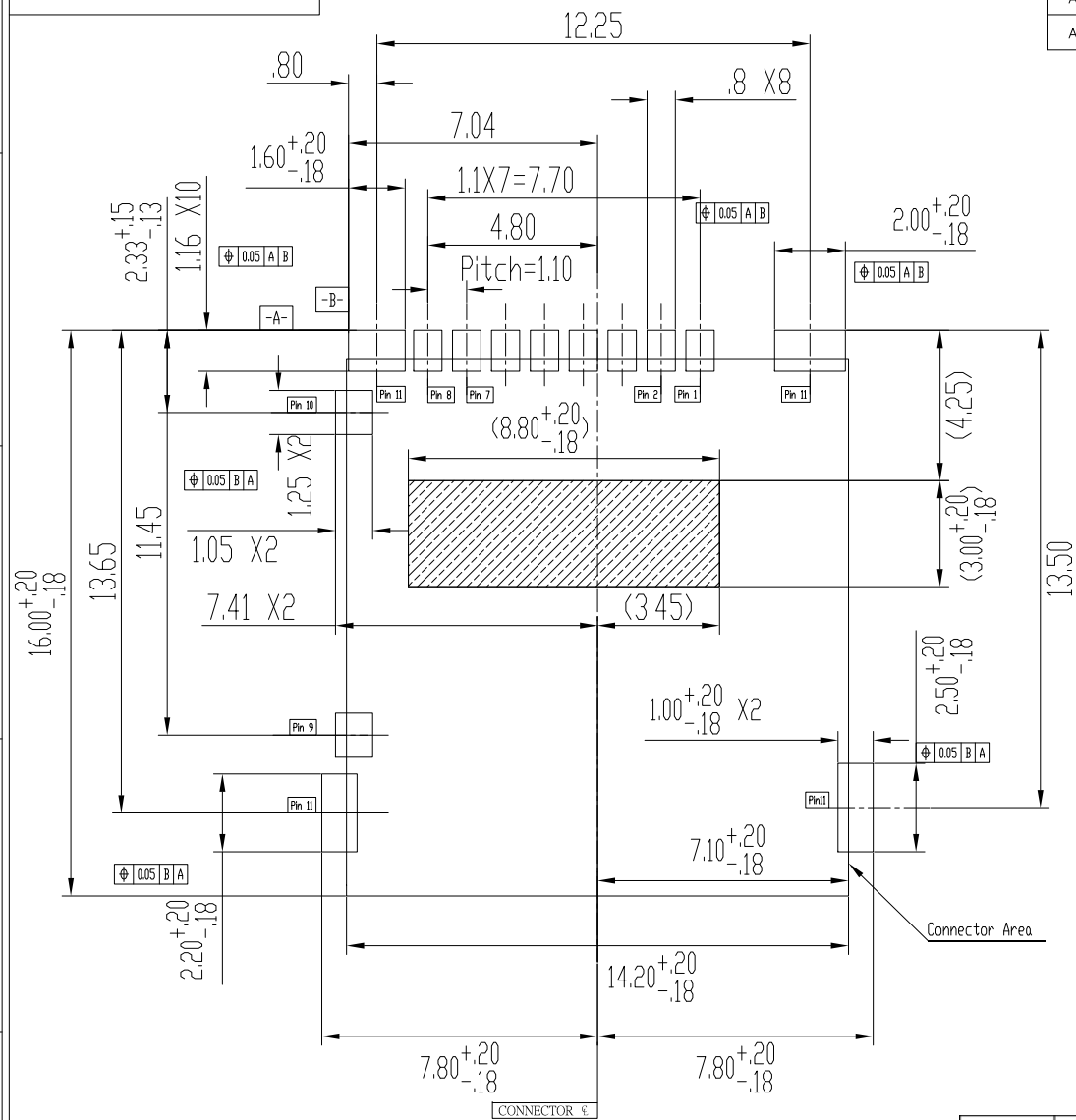


Micro SD C/D GND (PIN 09) (PIN 10)	Micro SD C/D GND (PIN 09) (PIN 10)
Card Extraction	Card Inserted
Micro SD Circuit	

NO	VARIETY	QTY	METERIAL	REMARK
Matrix Electronics Co.,Ltd				
TOLERANCE: X:X ±0.15 X:XX ±0.10 X:XXX ±0.05 ANGLE: ±1°		DESIGN BY : Phebe Su	DATE : 2016/08/19	PART NAME: Micro-SD Push Normal Type <i>(Connector(Hs:150mm))</i>
CHECKED BY: Vicky Hsieh		DATE : 2016/08/19	PART NO.	MMS-01-01-08-15-18
APPROVED BY1: Richard Hsieh		DATE : 2016/08/19	MOLD NO.	NA
APPROVED BY2: Richard Hsieh		DATE : 2016/08/19	DRAW NO.	
SCALE:1:1 SIZE:A4		SHEET NO.	1 OF 2	

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MATRIX PART NO:

Diagram illustrating the pin header layout for the MMS-01-01-08-15-18 component. The pins are labeled as follows:

- 01: Push
- 02: Non-Push
- 03: Plating
- 04: G/F
- 05: 30:30u
- 06: 30:30u

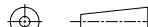
The labels are connected to the pins by lines. The labels are: Matrix MICRO SD, 01: Push, 02: Non-Push, Plating, 01:G/F, 30:30u, Series Number, Height, Pin number, 06:6pin, 08:8pin.

RECOMMEND P.C.B LAYOUT

 =PATTERN PROHIBITED AREA

 = TIN AREA

		NO	VARIETY	QTY	MATERIAL	REMARK	
11	Cover-GND	 <i>Matrix Electronics Co.,Ltd</i>					
10	Micro SD-GND						
09	Micro SD-CD						
08	Micro-SD_DAT1						
07	Micro-SD_DAT0						
06	Micro-SD_VSS						
05	Micro-SD_CLK						
04	Micro-SD_VDD						
03	Micro-SD_CMD						
02	Micro-SD_CD/DAT3						
01	Micro-SD_DAT2						
Pin NO.	Description						

TOLERANCE: X.X ±0.15 X.XX ±0.10 X.XXX ±0.05 ANGLE: ±1°		DESIGN BY : Phebe Su	DATE : 2016/08/19	PART NAME: Micro-SD Push Normal Type <i>Connector(Ht:150mm)</i>	
UNIT: mm [inch]		CHECKED BY: Vicky Hsieh	DATE : 2016/08/19	PART NO.	MMS-01-01-08-15-18
		APPROVED BY1: Richard Hsieh	DATE : 2016/08/19	MOLD NO.	NA
SCALE:1:1 SIZE:A4		APPROVED BY2: Richard Hsieh	DATE : 2016/08/19	DRAW NO.	
				SHEET NO.	2 OF 2